



80-M3166BA125AS02-K849G32

datasheet

Vincotech

MiniSKiiP® CON 3		1600 V / 125 A
Features		
	<ul style="list-style-type: none">• 3-phase full controlled input rectifier with brake chopper• Fast Trench IGBT• Temperature sensor integrated	
Target applications		Schematic
	<ul style="list-style-type: none">• Industrial Drives	
Types		
	<ul style="list-style-type: none">• 80-M3166BA125AS02-K849G32	

Maximum Ratings

$T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Thyristor				
Repetitive peak reverse voltage	V_{RRM}		1600	V
Forward average current	I_{FAV}		125	A
Surge forward current	I_{FSM}		1250	A
I^2t value	I^2t	$t_p = 10 \text{ ms}$ $T_j = 130^\circ\text{C}$	7810	A^2s
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80^\circ\text{C}$	168	W
Maximum Junction Temperature	T_{jmax}		130	$^\circ\text{C}$



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Maximum Ratings

$T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Brake Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C		150	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	450	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80^\circ\text{C}$	453	W
Gate-emitter voltage	V_{GES}		± 20	V
Short circuit ratings	t_{SC} V_{CC}	$T_j \leq 150^\circ\text{C}$ $V_{GE} = 15\text{ V}$	10 800	μs V
Maximum junction temperature	T_{jmax}		175	$^\circ\text{C}$

Brake Diode

Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80^\circ\text{C}$	112	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave $t_p = 10\text{ ms}$	900	A
Surge current capability	I^2t	$T_j = 150^\circ\text{C}$	4050	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80^\circ\text{C}$	244	W
Maximum junction temperature	T_{jmax}		175	$^\circ\text{C}$

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	$^\circ\text{C}$
Operation temperature under switching condition	T_{op}		-40...($T_{jmax} - 25$)	$^\circ\text{C}$

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	5500	V
		AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance		With std lid For more informations see handling instruction	6,3	mm
Clearance		With std lid For more informations see handling instruction	6,3	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production



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Characteristic Values

Parameter	Symbol	Conditions						Value			Unit
			V_{GE} [V]	V_{CE} [V]	I_c [A]	I_D [A]	T_j [°C]	Min	Typ	Max	
			V_{GS} [V]	V_{DS} [V]	I_F [A]						

Rectifier Thyristor

Static

Forward voltage	V_F				125	25 125		1,11 1,06	1,4		V
Threshold voltage (for power loss calc. only)	V_{to}					130			0,85		V
Slope resistance (for power loss calc. only)	r_t					130			3,2		mΩ
Critical rate of rise of off-state voltage	$(dv/dt)_{cr}$					130			1000		V/μs
Critical rate of rise of on-state current	$(di/dt)_{cr}$					130			100		A/μs
Circuit commutated turn-off time	t_q					130		150			μs
Holding current	I_H					25			220		mA
Latching current	I_L					25			550		mA
Gate trigger voltage	V_{GT}					25			1,98		V
Gate trigger current	I_{GT}					25			100		mA
Gate non-trigger voltage	V_{GD}					130	0,25				V
Gate non-trigger current	I_{GD}					115	6				mA

Thermal

Thermal resistance chip to sink	$R_{th(j-s)}$	$\lambda_{paste} = 2,5 \text{ W/mK}$ (HPTP)						0,30		K/W
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Characteristic Values

Parameter	Symbol	Conditions						Value			Unit
			V_{GE} [V]	V_{CE} [V]	I_c [A]	T_1 [°C]	Min	Typ	Max		
			V_{GS} [V]	V_{DS} [V]	I_D [A]	I_F [A]					

Brake Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,0052	25	5,3	5,8	6,4	V
Collector-emitter saturation voltage	V_{CESat}		15		150	125 150	1,58	2,72 3,48 3,68	2,07	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			2	µA
Gate-emitter leakage current	I_{GES}		20	0		25			240	nA
Internal gate resistance	r_g							5		Ω
Input capacitance	C_{ies}	$f = 1 \text{ Mhz}$	0	25	25			8600		pF
Reverse transfer capacitance	C_{res}							320		

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{\text{paste}} = 2,5 \text{ W/mK}$ (HPTP)						0,22		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{goff} = 4 \Omega$ $R_{gon} = 4 \Omega$	15/0	700	149	25		64		ns
Rise time	t_r					125		65		
						150		66		
Turn-off delay time	$t_{d(off)}$					25		71		
						125		71		
Fall time	t_f					150		70		
Turn-on energy (per pulse)	E_{on}					25		597		
		$Q_{rFWD} = 9,6 \mu\text{C}$ $Q_{rFWD} = 19,7 \mu\text{C}$ $Q_{rFWD} = 24,5 \mu\text{C}$	125			125		681		
						150		708		
Turn-off energy (per pulse)	E_{off}					25		28		
						125		45		
						150		90		
						25		26,61		
						125		35,58		
						150		38,38		
						25		11,67		
						125		16,84		
						150		18,78		



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Characteristic Values

Parameter	Symbol	Conditions						Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_c [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

Brake Diode

Static

Forward voltage	V_F				150	25 150		2,50 2,53	2,7	V
Reverse leakage current	I_R			1200		25 150			180 28000	µA

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 2,5 \text{ W/mK}$ (HPTP)						0,39		K/W
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Dynamic

Peak recovery current	I_{RRM}	$di/dt = 800 \text{ A/}\mu\text{s}$ $di/dt = 1170 \text{ A/}\mu\text{s}$ $di/dt = 1197 \text{ A/}\mu\text{s}$	15/0	700	149	25		41		A
Reverse recovery time	t_{rr}					125		54		
						150		61		
Recovered charge	Q_r					25		461		
						125		625		
						150		713		ns
Recovered charge	Q_r					25		9,61		
						125		19,74		
						150		24,48		µC
Reverse recovered energy	E_{rec}					25		3,57		
						125		7,41		mWs
						150		9,26		
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25		98		
						125		61		A/µs
						150		66		

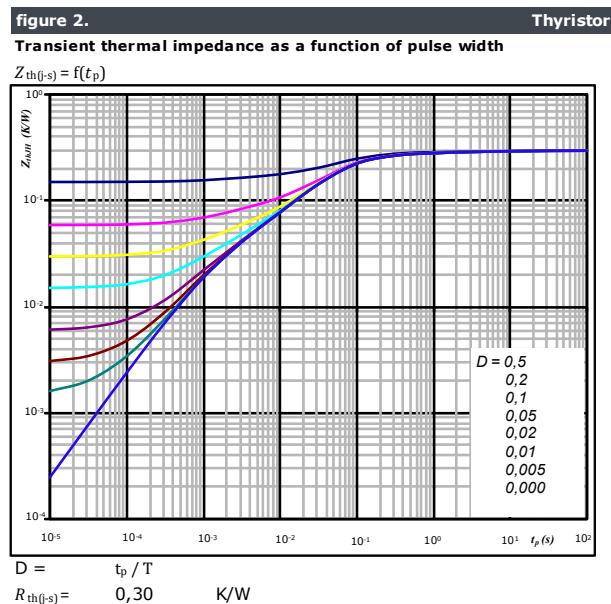
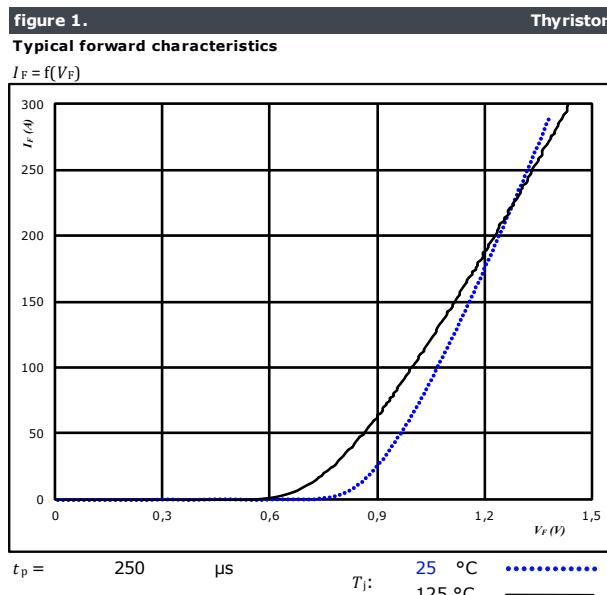
Thermistor

Rated resistance	R				25		1		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1670 \Omega$			100	-2		+2	%
R_{100}	R				100		1670		Ω
Power dissipation constant					25		0,76		mW/K
A-value	$A_{(25/50)}$				25		$7,635 \cdot 10^{-3}$		1/K
B-value	$B_{(25/100)}$				25		$1,731 \cdot 10^{-5}$		1/K²
Vincotech PTC Reference							E		



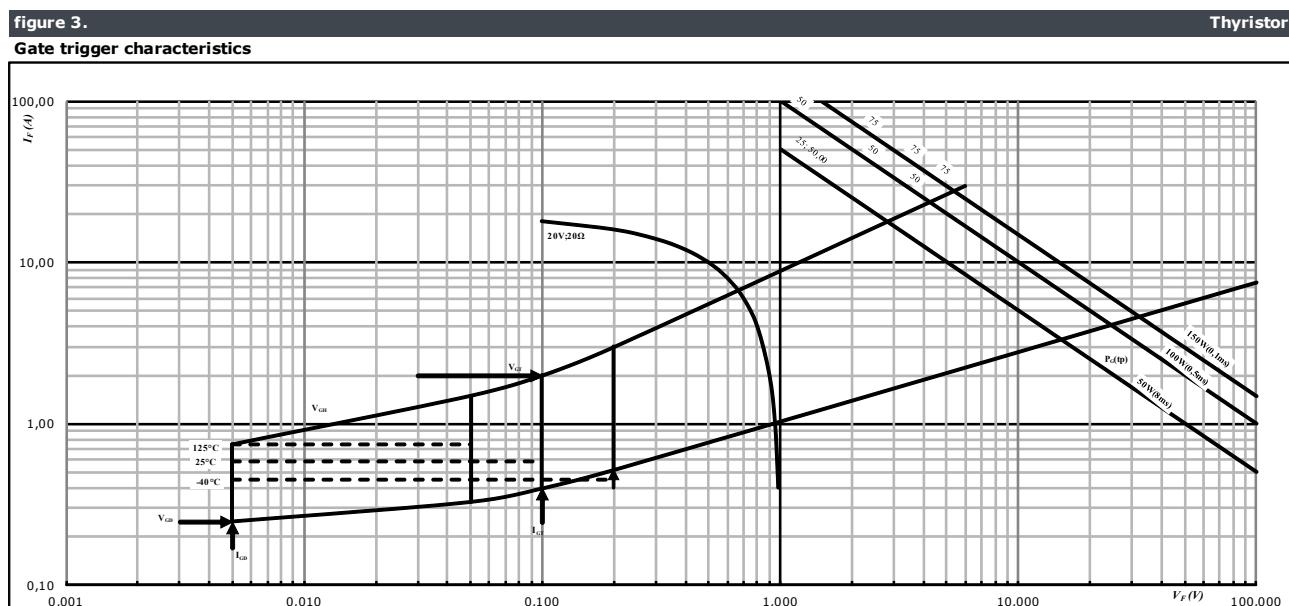
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Rectifier Thyristor Characteristics



FWD thermal model values

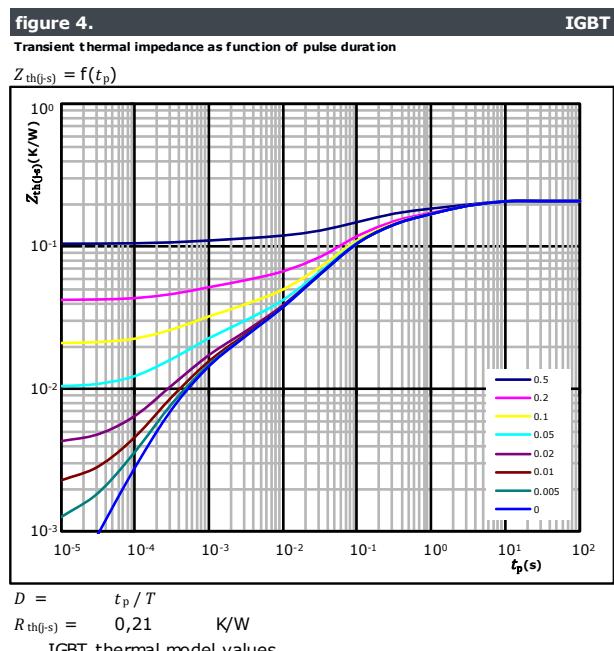
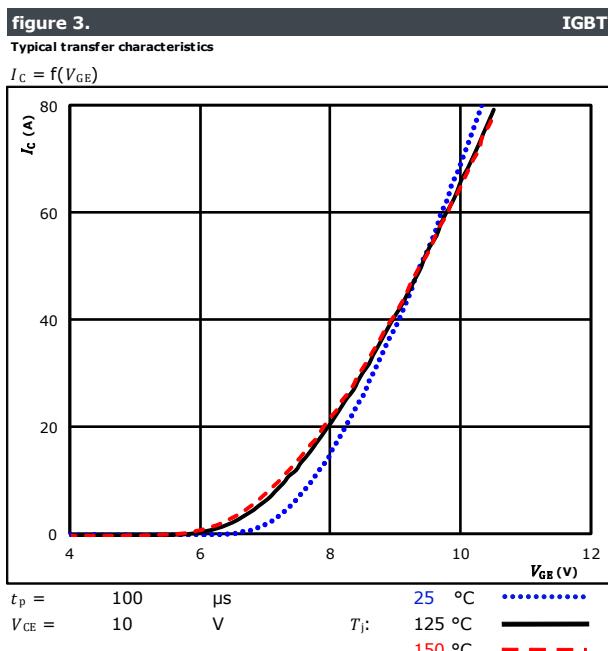
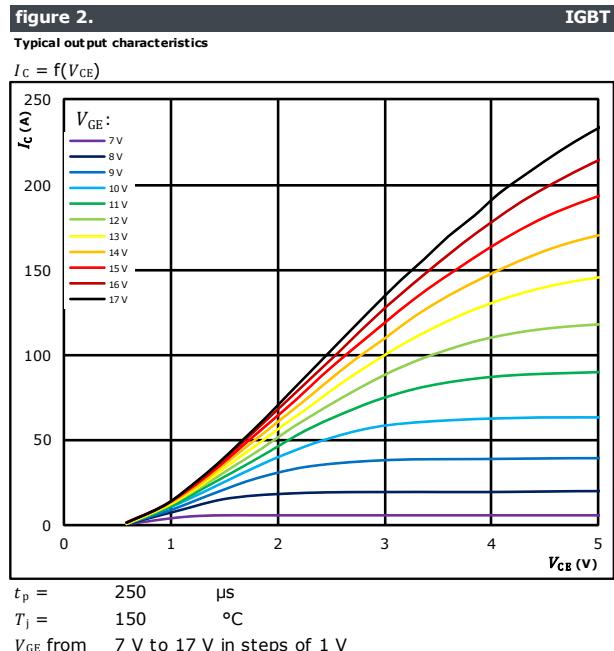
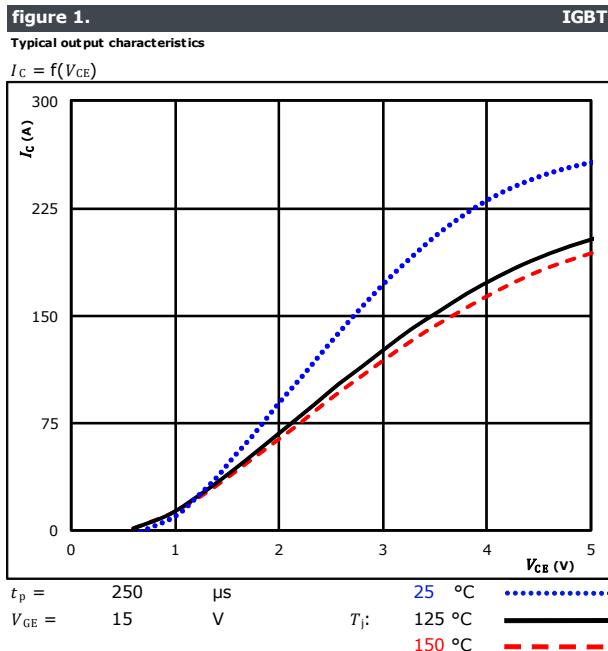
R (K/W)	Tau (s)
1,10E-02	8,76E+00
2,07E-02	7,46E-01
5,49E-02	1,33E-01
1,59E-01	4,45E-02
2,97E-02	8,66E-03
7,88E-02	1,33E-03





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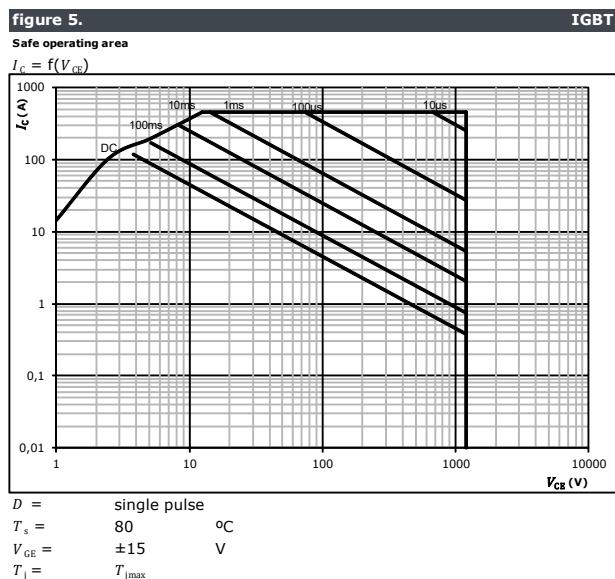
Brake Switch Characteristics





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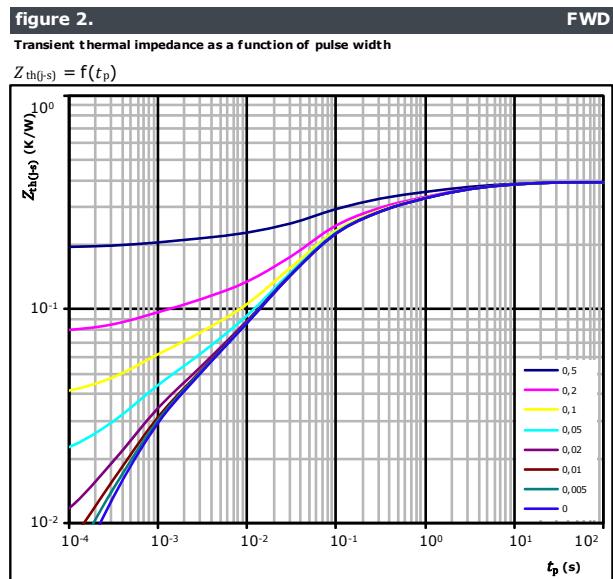
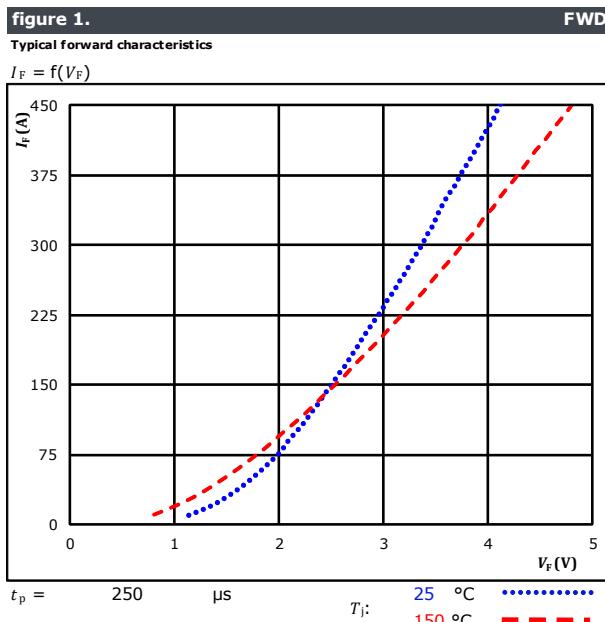
Brake Switch Characteristics





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Brake Diode Characteristics

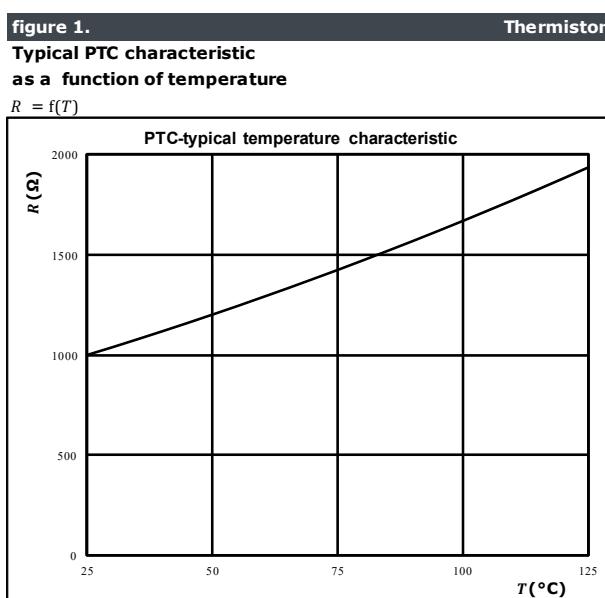


$D = t_p / T$
 $R_{th(f-s)} = 0,39 \text{ K/W}$

FWD thermal model values

R (K/W)	τ (s)
3,07E-02	8,01E+00
6,95E-02	1,36E+00
7,63E-02	2,37E-01
1,50E-01	4,99E-02
3,25E-02	7,73E-03
1,77E-02	1,17E-03
1,32E-02	4,59E-04

Thermistor Characteristics





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Brake Switching Characteristics

figure 1. IGBT
Typical switching energy losses as a function of collector current

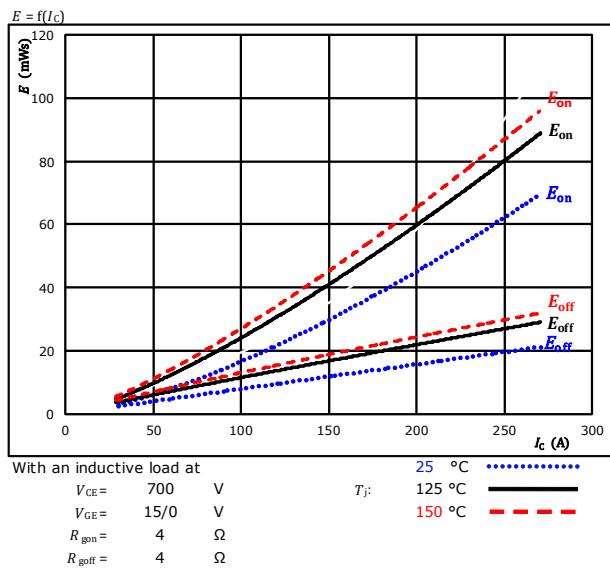


figure 2. IGBT
Typical switching energy losses as a function of gate resistor

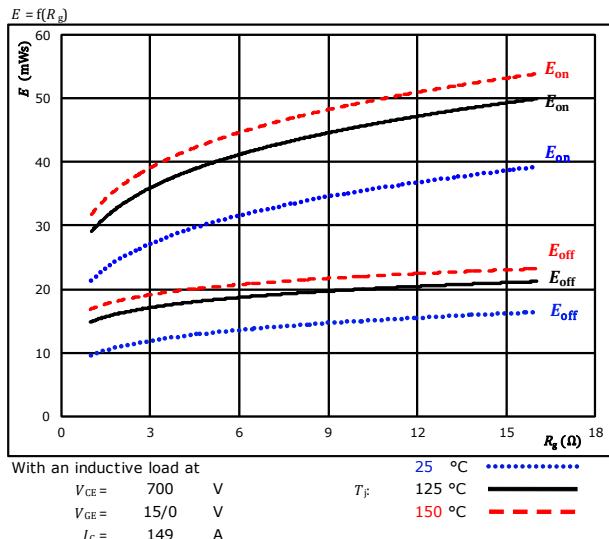


figure 3. FWD
Typical reverse recovered energy loss as a function of collector current

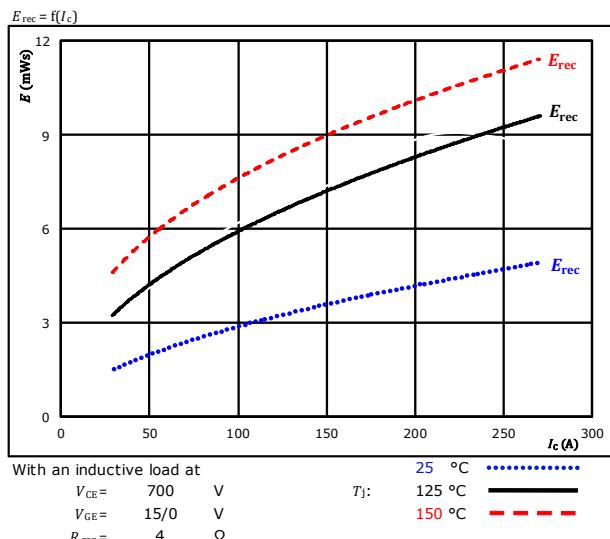
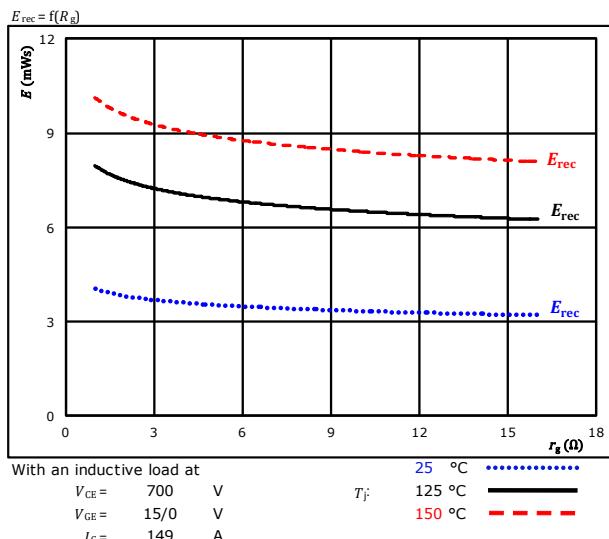


figure 4. FWD
Typical reverse recovered energy loss as a function of gate resistor



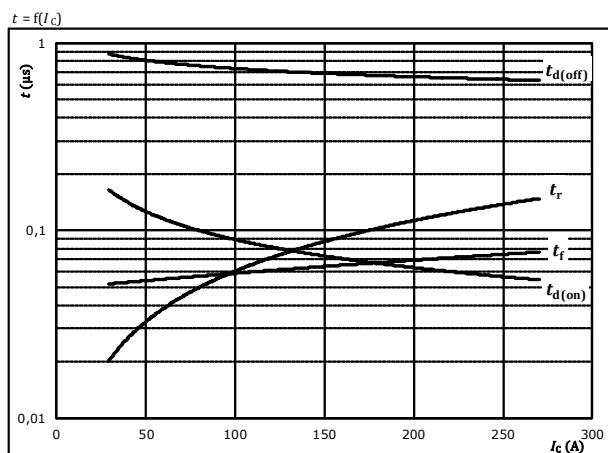


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Brake Switching Characteristics

figure 5. IGBT

Typical switching times as a function of collector current

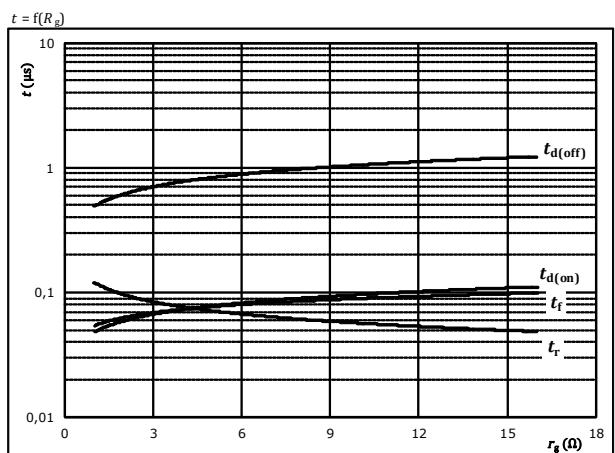


With an inductive load at

$T_J =$	150	°C
$V_{CE} =$	700	V
$V_{GE} =$	15/0	V
$R_{gon} =$	4	Ω
$R_{goff} =$	4	Ω

figure 6. IGBT

Typical switching times as a function of gate resistor

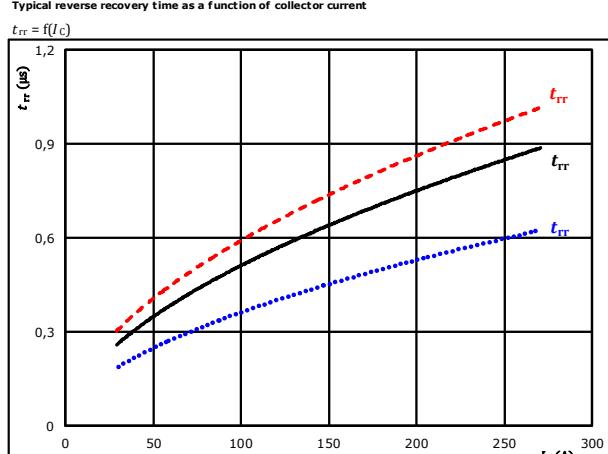


With an inductive load at

$T_J =$	150	°C
$V_{CE} =$	700	V
$V_{GE} =$	15/0	V
$I_C =$	149	A

figure 7. FWD

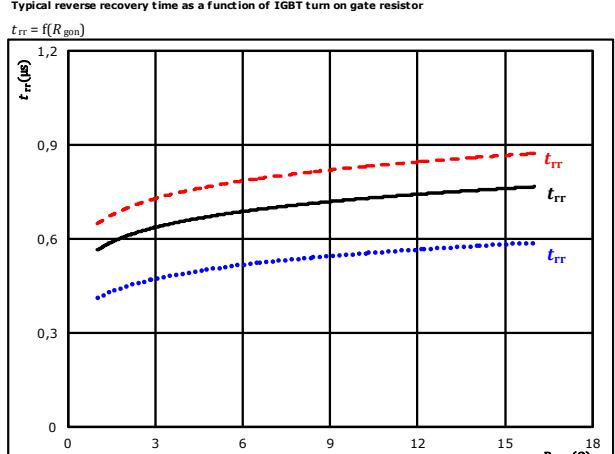
Typical reverse recovery time as a function of collector current



At	$V_{CE} =$	700	V	25 °C
	$V_{GE} =$	15/0	V	$T_J =$	125 °C
	$R_{gon} =$	4	Ω		150 °C

figure 8. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

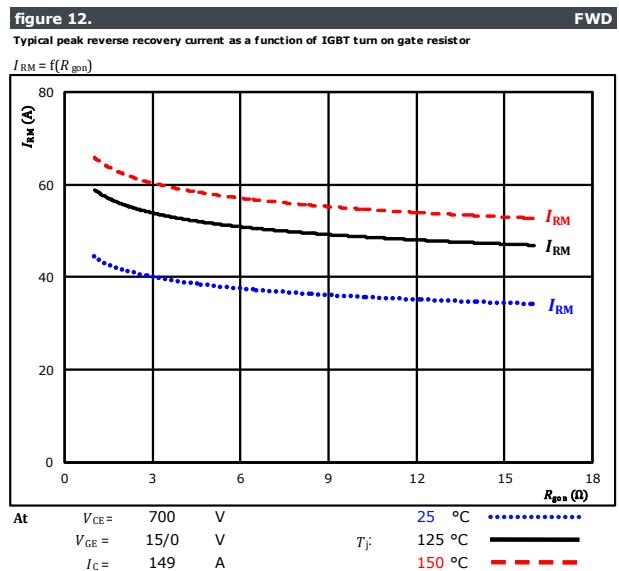
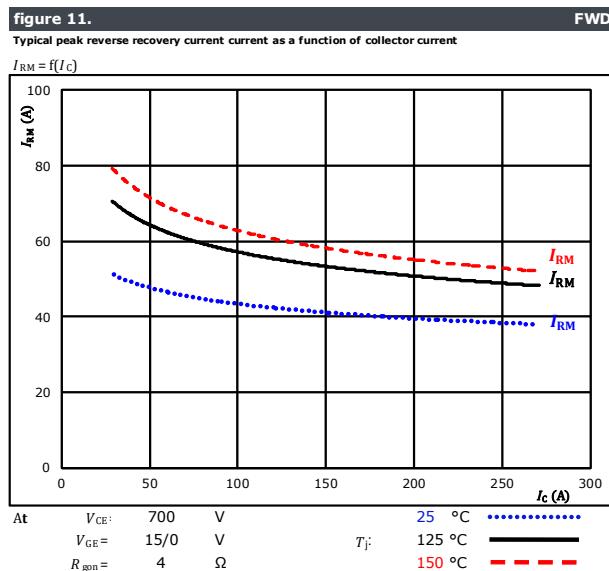
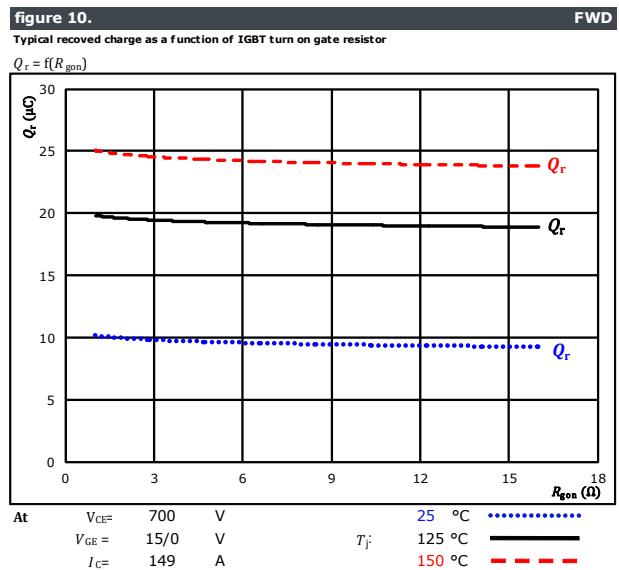
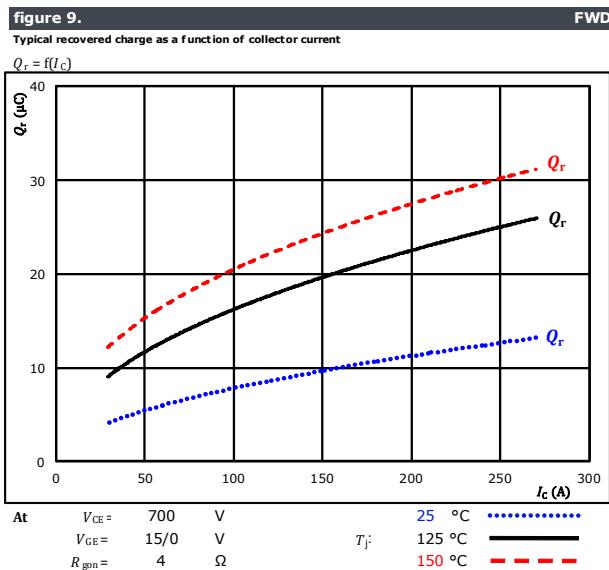


At	$V_{CE} =$	700	V	25 °C
	$V_{GE} =$	15/0	V	$T_J =$	125 °C
	$I_C =$	149	A		150 °C



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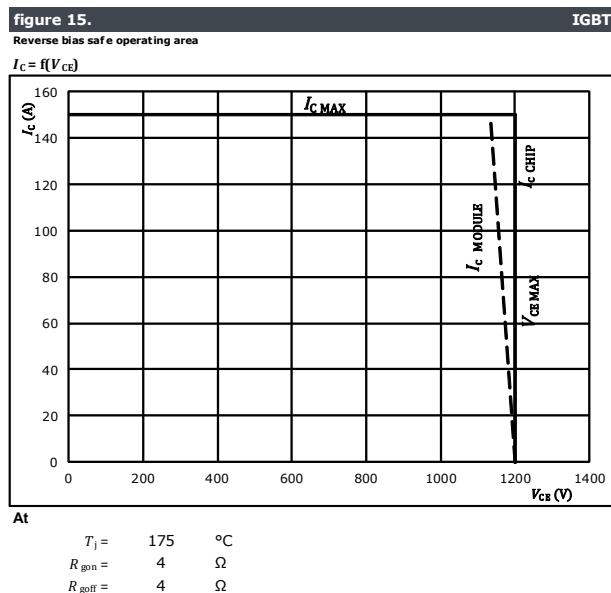
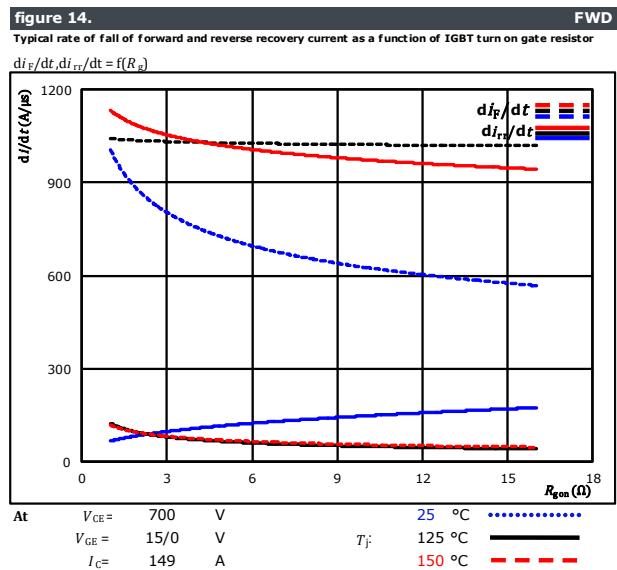
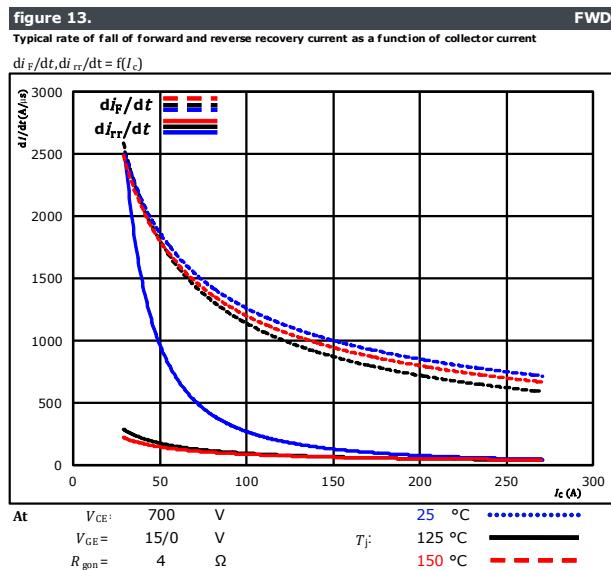
Brake Switching Characteristics





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Brake Switching Characteristics





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Brake Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	4 Ω
R_{goff}	=	4 Ω

figure 1.

IGBT

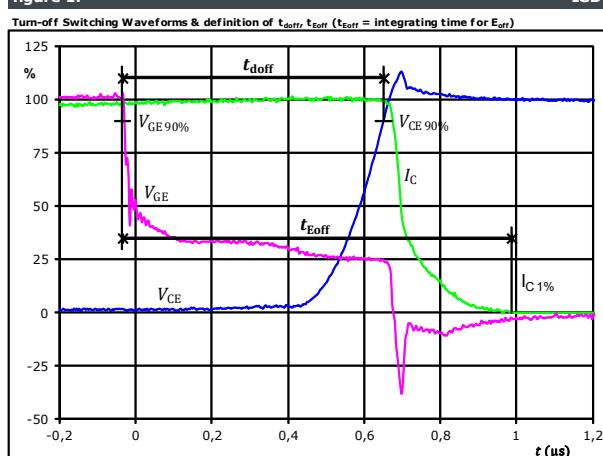


figure 2.

IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

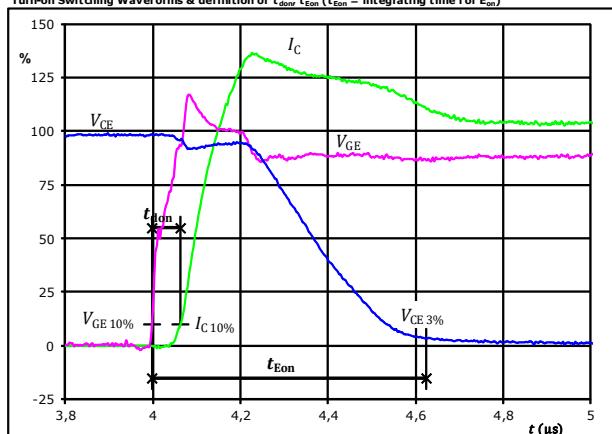


figure 3.

IGBT

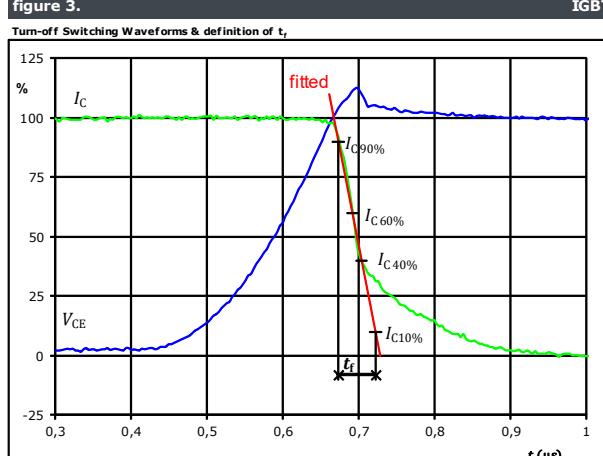
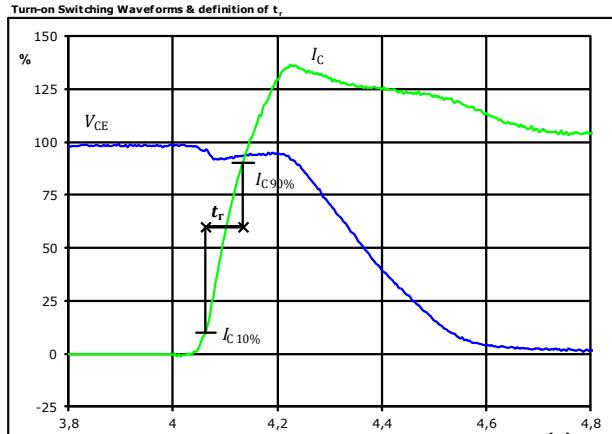


figure 4.

IGBT

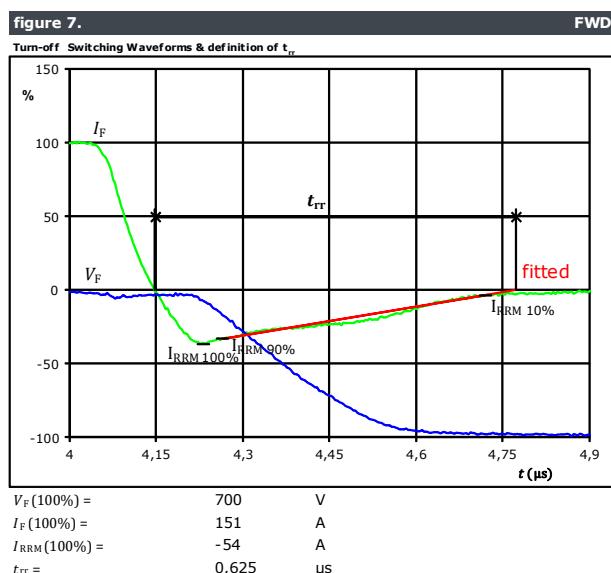
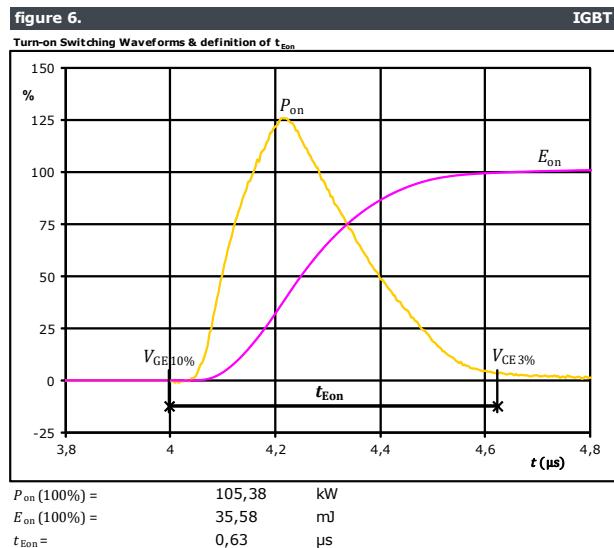
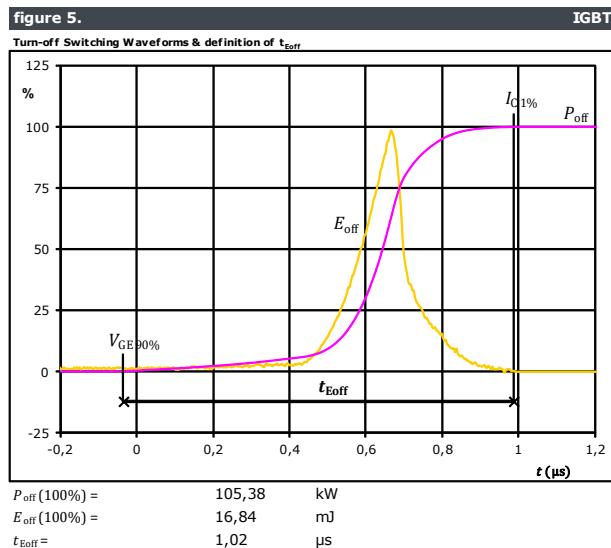
Turn-on Switching Waveforms & definition of t_r





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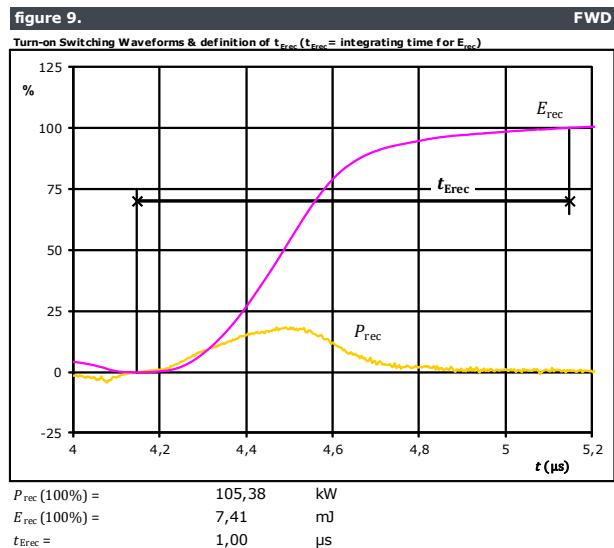
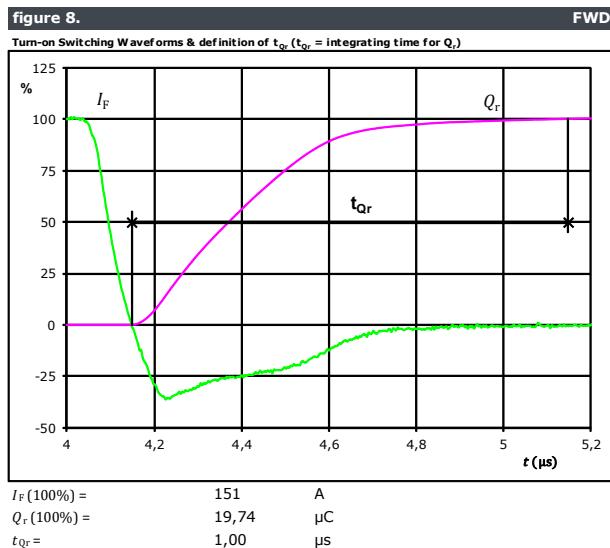
Brake Switching Characteristics





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Brake Switching Characteristics





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Ordering Code & Marking									
Version					Ordering Code				
With std lid (6.5mm height) + no thermal grease					80-M3166BA125AS02-K849G32-/0A/				
With thin lid (2.8mm height) + no thermal grease					80-M3166BA125AS02-K849G32-/0B/				
With std lid (6.5mm height) + thermal grease (0.8 W/mK, P12, silicone-based)					80-M3166BA125AS02-K849G32-/1A/				
With thin lid (2.8mm height) + thermal grease (0.8 W/mK, P12, silicone-based)					80-M3166BA125AS02-K849G32-/1B/				
With std lid (6.5mm height) + thermal grease (2.5 W/mK, TG20032, silicone-free)					80-M3166BA125AS02-K849G32-/4A/				
With thin lid (2.8mm height) + thermal grease (2.5 W/mK, TG20032, silicone-free)					80-M3166BA125AS02-K849G32-/4B/				
With std lid (6.5mm height) + thermal grease (2.5 W/mK, HPTP, silicone-based)					80-M3166BA125AS02-K849G32-/5A/				
With thin lid (2.8mm height) + thermal grease (2.5 W/mK, HPTP, silicone-based)					80-M3166BA125AS02-K849G32-/5B/				
 NN-NNNNNNNNNNNN TTTTTVVV WWYY UL VIN LLLL SSSS					Text NN-NNNNNNNNNNNN-TTTTTVV Datamatrix TTTTTVVV	Name WWYY	Date code UL VIN	UL & VIN LLLL	Lot SSSS
					Type&Ver Type&Ver	Lot number LLLL	Serial SSSS	Date code WWYY	

Outline									
PCB pad table									
Pin	X	Y	Function	Pin	X	Y	Function		
1	15,83	-25,3	G36	62					
2			Not assembled	63					
3	15,83	-3,2	G35	64	-40,22	-15,7	ACIn1		
4				65	-40,22	-12,5	ACIn1		
5			Not assembled	66	-40,22	-9,3	ACIn1		
6				67	-40,22	-6,09	ACIn1		
7	15,83	15,7	DC-	68	-50,18	-25,3	DC+Rect		
8	15,83	18,9	DC-	69	-50,18	-22,1	DC+Rect		
9	15,83	22,1	DC-	70	-50,18	-18,9	DC+Rect		
10	15,83	25,3	DC-	71	-50,18	-15,7	DC+Rect		
11	8,13	-25,3	Therm1	72	-50,18	-9,5	DC+Br		
12	8,13	-22,1	Therm2	73	-50,18	-6,3	DC+Br		
13	8,13	22,1	DC-	74	-50,18	6,3	DC+Br		
14	8,13	25,3	DC-	75	-50,18	9,5	DC+Br		
15	1,82	-15,38	ACIn3	76	-50,18	22,1	Br		
16	1,82	-12,18	ACIn3	77	-50,18	25,3	Br		
17	1,82	-8,98	ACIn3	78	-53,82	-25,3	DC+Rect		
18	1,82	-5,79	ACIn3	79	-53,82	-22,1	DC+Rect		
19	0,43	22,1	DC-	80	-53,82	-18,9	DC+Rect		
20	0,43	25,3	DC-	81	-53,82	-15,7	DC+Rect		
21	-1,07	-25,3	G34	82	-53,82	-9,5	DC+Br		
22	-1,82	-15,38	ACIn3	83	-53,82	-6,3	DC+Br		
23	-1,82	-12,18	ACIn3	84			Not assembled		
24	-1,82	-8,98	ACIn3	85	-53,82	6,3	DC+Br		
25	-1,82	-5,79	ACIn3	86	-53,82	9,5	DC+Br		
26	-5,82	3,95	G33	87	-53,82	22,1	Br		
27	-7,27	22,1	S27	88	-53,82	25,3	Br		
28	-7,27	25,3	G27						
29			Not assembled						
30									
31	-16,05	-15,02	ACIn2						
32	-16,05	-11,82	ACIn2						
33	-16,05	-8,63	ACIn2						
34	-16,05	-5,42	ACIn2						
35	-19,22	-25,3	G32						
36	-19,7	-15,02	ACIn2						
37	-19,7	-11,82	ACIn2						
38	-19,7	-8,62	ACIn2						
39	-19,7	-5,42	ACIn2						
40			Not assembled						
41									
42									
43			Not assembled						
44									
45									
46									
47									
48			Not assembled						
49	-32,82	11,94	G31						
50	-35,68	22,1	Br						
51	-35,68	25,3	Br						
52			Not assembled						
53									
54	-36,58	-15,7	ACIn1						
55	-36,58	-12,5	ACIn1						
56	-36,58	-9,3	ACIn1						
57	-36,58	-6,1	ACIn1						
58			Not assembled						
59									
60	-39,32	22,1	Br						
61	-39,32	25,3	Br						

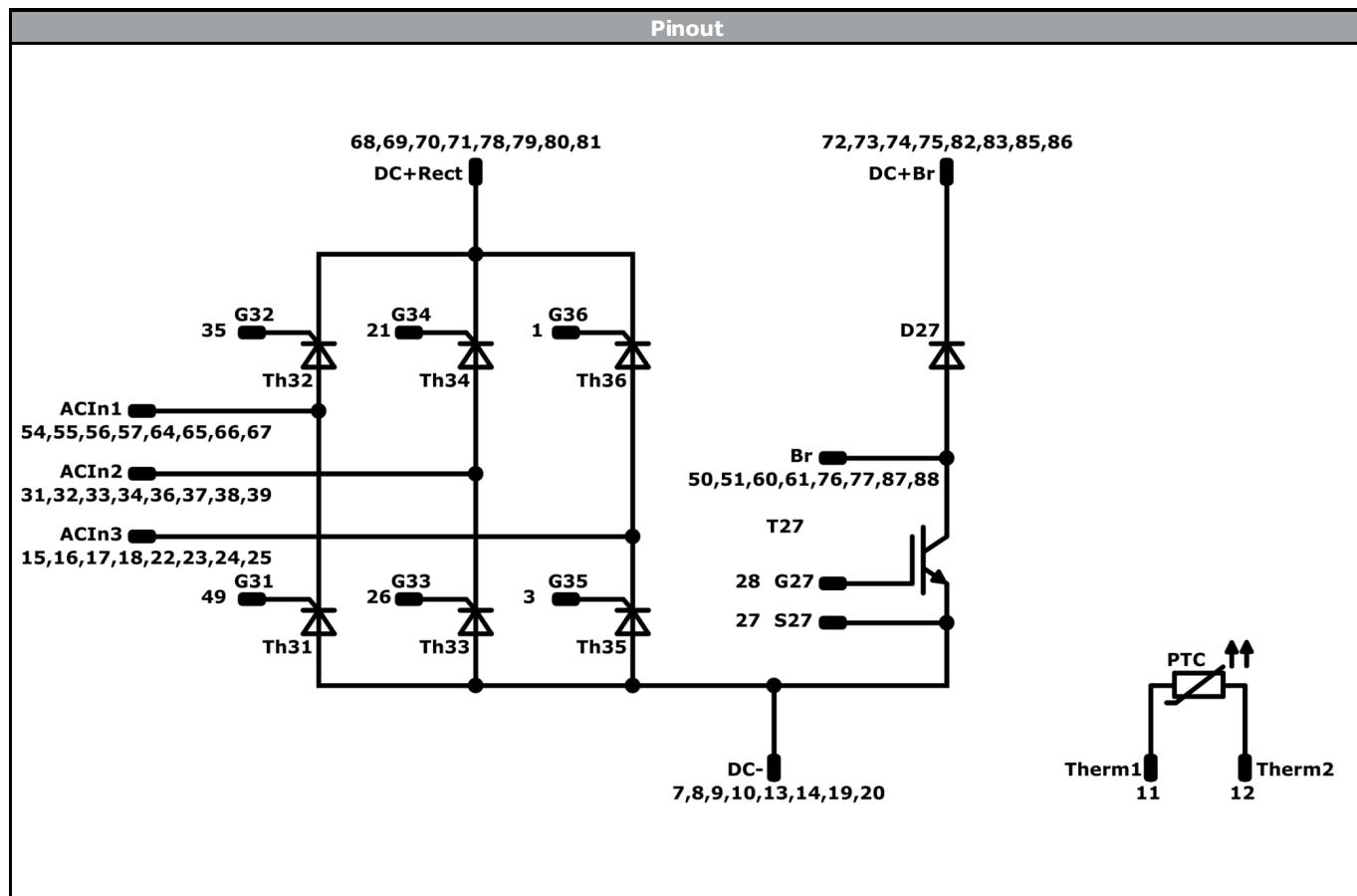
The PCB layout diagram shows the physical arrangement of components on the board. Components include surface-mount packages (SMDs) and through-hole components. Pin numbers are indicated for each pad, corresponding to the PCB pad table above. The layout is organized into several functional groups, such as the central IC area, peripheral pads, and various mounting holes.



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datasheet

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Identification

ID	Component	Voltage	Current	Function	Comment
Th31, Th32, Th33, Th34, Th35, Th36	Rectifier Thyristor	1600 V	125 A	Rectifier Thyristor	
T27	IGBT	1200 V	150 A	Brake Switch	
D27	FWD	1200 V	150 A	Brake Diode	
Rt	PTC			Thermistor	

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Packaging instruction			
Standard packaging quantity (SPQ) 48	>SPQ	Standard	<SPQ Sample

Handling instruction			
Handling instructions for MiniSkiip® 3 packages see vincotech.com website.			

Package data			
Package data for MiniSkiip® 3 packages see vincotech.com website.			

UL recognition and file number			
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.			

Document No.:	Date:	Modification:	Pages
80-M3166BA125AS02-K849G32-D1-14	11 Dec. 2017		

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